	REVISION (NOR)		1. DATE (YYMMDD) 93-11-18	Form Approved OMB No. 0704-0188
This revision described below document listed.	has been authorized t	or the		
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4. ORIGINATOR	b. ADDRESS (Street, City, Code)		5. CAGE CODE 67268	6. NOR NO. 5962-R045-94
a. TYPED NAME (First, Middle Initial, Last) N. A.	Defense Electronics 1507 Wilmington Pike Dayton, OH 45444-527	<u> </u>	7. CAGE CODE 67268	8. DOCUMENT NO. 85030
9. TITLE OF DOCUMENT		10. REVISION	LETTER	11. ECP NO.
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14. THIS SECTION FOR GOVERNMENT U	SE ONLY			
a. (X one) X (1) Existing	g document supplemented b	y the NOR may l	oe used in manufa	acture.
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d. TITLE	e. SIGNATURE		f. DATE SIGNED (YYMMDD)	
Chief, Electronic Components Branch	Kendall A. Cottongin	a .	93-11-18	
15a. ACTIVITY ACCOMPLISHING REVISION	b. REVISION COMPLETED (Si		c. DATE SIGNED (YYMMDD)	
DESC-ECT	Gary Zahn		93-11-18	

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a. TYPED NAME (First, Middle	Defense Electronics		7. CAGE CODE	8. DOCUMENT NO.
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9. TITLE OF DOCUMENT		10. REVISION	LETTER	11. ECP NO.
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	es; for sheets 1 and 4 del		stitute "D".	
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**REVISION LEVEL** 

- 1. SCOPE
- 1.1 Scope. This drawing describes device requirements for class H hybrid microcircuits to be processed in accordance with MIL-H-38534.
- 1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Generic number	<u>Circuit function</u>
2700	Precision +10.000-volt reference
2702	Precision ±10.000-volt reference
2701	Precision -10.000-volt reference
	2700 2702

1.2.2 <u>Case outline(s)</u>. The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
C	GDIP1-T14	14	Dual-in-line
X	See figure 1	14	Dual-in-line
Υ	See figure 1	14	Dual-in-line
3	CQCC1-N28	28	Square leadless chip-carrier

- 1.2.3 <u>Lead finish</u>. The lead finish shall be as specified in MIL-H-38534. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.
  - 1.3 Absolute maximum ratings.

Supply voltage (V <sub>S</sub> ):	+20 V dc
V <sub>CC</sub> (device types 01, 02, 03, 04)	-20 V dc
V <sub>EE</sub> (device types 03, 04, 05, 06)	-20 V uc
Power dissipation ( $P_D$ ), $T_A = +25^{\circ}$ C:	200 \
Device types 01, 02, 05, 06	300 mW
Device types 03, 04	450 mW
Storage temperature range	-65° C to +150° C
Lead temperature (soldering, 10 seconds)	+300° C
Short circuit protection (to GND)	Continuous
Thermal resistance:	
Junction-to-case ( $\theta_{JC}$ ):	
Cases C and 3	See MIL-STD-1835
Case X	7° C/W
Case Y	8° C/W
Junction-to-ambient (θ μ):	
Case X	30° C/W
Case Y	25° C/W

1.4 Recommended operating conditions.

Supply voltage range (V <sub>CC</sub> )	+13.5 V dc to +16.5 V dc
Supply voltage range (V <sub>EE</sub> )	-13.5 V dc to -16.5 V dc
Output current	5 mA 1/
Ambient operating temperature range (T <sub>A</sub> )	-55° C to +125° C

1/ With resistive load to pin 7 (common).

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#### 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification and standards</u>. Unless otherwise specified, the following specification and standards of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein

**SPECIFICATION** 

**MILITARY** 

MIL-H-38534 - Hybrid Microcircuits, General Specification for.

**STANDARDS** 

**MILITARY** 

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

MIL-STD-1835 - Microcircuit Case Outlines.

(Copies of the specification and standards required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

### 3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with MIL-H-38534 and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-H-38534 and herein.
  - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.2 herein.
  - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.
  - 3.2.3 Trim circuits. The trim circuits shall be as specified on figure 3.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-H-38534. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in QML-38534 (see 6.6 herein).
- 3.6 <u>Manufacturer eligibility</u>. In addition to the general requirements of MIL-H-38534, the manufacturer of the part described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, produced on the certified line, for each device type listed herein. The data should also include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DESC-EC) upon request.
- 3.7 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in QML-38534 (see 6.6 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-H-38534 and the requirements herein.
- 3.8 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-H-38534 shall be provided with each lot of microcircuits delivered to this drawing.

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		TABLE I. <u>E</u>	lectrical perform	ance characteris	tics.			
Test	Symbol	Conditions <u>1</u> / -55° C ≤ T <sub>A</sub> ≤ +125° C		Group A subgroups	Device type	Limit	6	Unit
		unless otherwise spec	ified			Min	Max	
Selection output error <u>2</u> /	+V <sub>R</sub>	+10.000 V output		4	01	-5.0	+5.0	mV
				5,6		-8.0	+8.0	_
		+10.000 V output		4	02,04	-2.5	+2.5	_
				5,6		-5.5	+5.5	_
		+10.000 V output		4	03	-5.0	+5.0	
				5,6		-10	+10	
	-V <sub>R</sub>	-10.000 V output		4	03,05	+5.0	-5.0	
				5,6		+10	-10	
		-10.000 V output	4	04,06	+2.5	-2.5		
				5,6	_	+5.5	-5.5	_
Interim output	+VRINT	+10.000 V output	Initial	1	01,02,	5	+5	-
error	' VRINT	T <sub>A</sub> = +25° C	End-point	_ '	03,04	-10	+10	_
	-V <sub>RINT</sub>	10.000 V output	Initial	1	03,04,	+5	-5	_
		-10.000 V output T <sub>A</sub> = +25° C		_ '	05,04,			
•	.,		End-point			+10	-10	_
Output adjust range for trim	<sup>+V</sup> RADJ	+10.000 V output, T <sub>A</sub> =	+25° C	1	01,02, 03,04	-20	+20	
circuits (see figure 3)	-V <sub>RADJ</sub>	-10.000 V output, T <sub>A</sub> = -	+25° C	1	03,04, 05,06	+20	-20	
Quiescent current I <sub>CC</sub>	V <sub>CC</sub> = +15	V, no load, T <sub>A</sub> = +25° C		1	01,02		+14	mA
		V <sub>CC</sub> = +15 V V <sub>EE</sub> = -15 V, no load T <sub>A</sub> = +25° C		1	03,04		+17	_
	lEE	V <sub>CC</sub> = +15 V, no load V <sub>EE</sub> = -15 V T <sub>A</sub> = +25° C		1	03,04		-4	
		V <sub>EE</sub> = -15 V, no load T <sub>A</sub> = +25° C		1	05,06		-9	

See footnotes at end of table.

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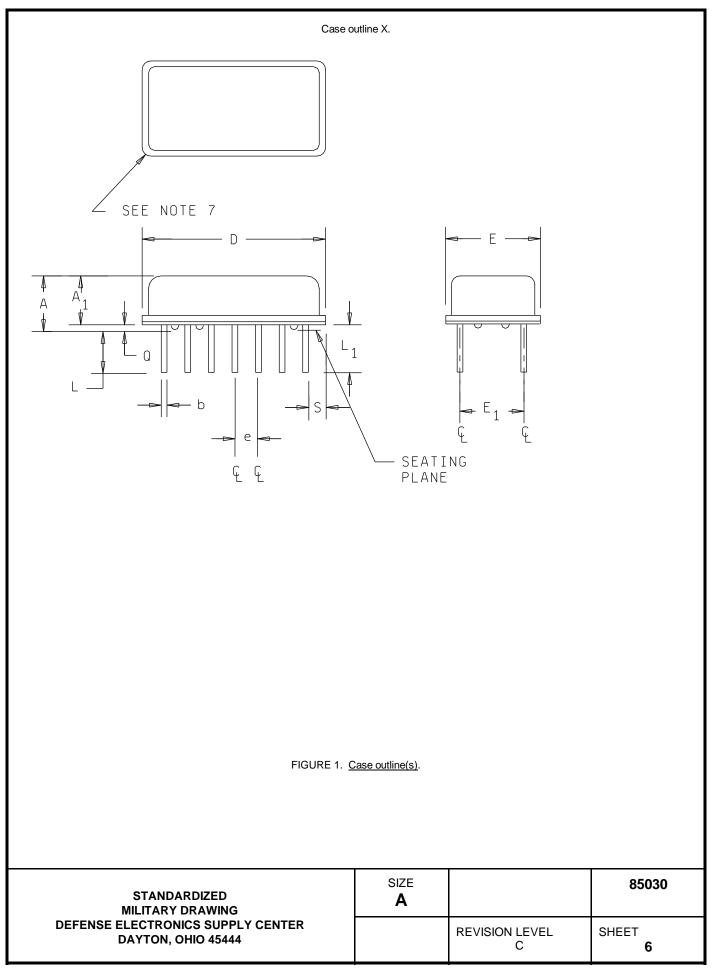
		TABLE I. Electrical performance	ce characteristics -	Continued.			
Test	Symbol	Conditions 1/	Group A	Device	Limit	Limits	
		-55° C ≤ T <sub>A</sub> ≤ +125° C unless otherwise specified	subgroups	type	Min	Max	
Line regulation	+V <sub>RL</sub>	+10 V output, $T_A = +25^{\circ} C$ , +13.5 V $\leq$ V <sub>CC</sub> $\leq$ +16.5 V	1	01,02, 03,04	-900	+900	μV
	-V <sub>RL</sub>	-10.000 V output, $T_A = +25^{\circ} C$ , -13.5 V $\leq$ V <sub>EE</sub> $\leq$ -16.5 V	1	03,04, 05,06	+900	-900	
	+VRLOAD	+10.000 V output, T <sub>A</sub> = +25°C, 0 ≤ I <sub>L</sub> ≤ 10 mA	1	01,02, 03,04	-500	+500	μV
	-VRLOAD	-10.000 V output, T <sub>A</sub> = +25° C, 0 ≤ I <sub>L</sub> ≤ 10 mA	1	03,04, 05,06	+500	-500	
Output current	+1_		1	01,02, 10		mA	
			2,3	03,04	5		
	-IL		1	03,04,		10	
			2,3	05,06		5	
Output noise <u>3</u> /		V <sub>OUT</sub> = 10 V, no load, 0.1 Hz ≤ BW ≤ 10 Hz, T <sub>A</sub> = +25° C	4	01,02, 03,04, 05,06		150	μV/ p-p

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 $<sup>\</sup>underline{1}$ / Unless otherwise specified,  $V_{IN}$  = +15 V,  $R_L$  = 2 k $\Omega$  to pin 7 (common), all tests after 3 minutes warm-up period.  $\underline{2}$ / Output voltage change as a function of temperature is determined using the box method. Each device is tested at -55° C, +25° C, and +125° C. At each temperature the output voltage (V<sub>OUT</sub>) must fall within the rectangular area bounded by the minimum and maximum temperatures. This method gives a maximum temperature coefficient of 9 ppm/° C and a typical value of 3 ppm/° C.

3/ Parameter shall be tested as part of device initial characterization and after design and process changes. Parameter shall be guaranteed to limits

specified in table I for all lots not specifically tested.



### Case outline X - Continued.

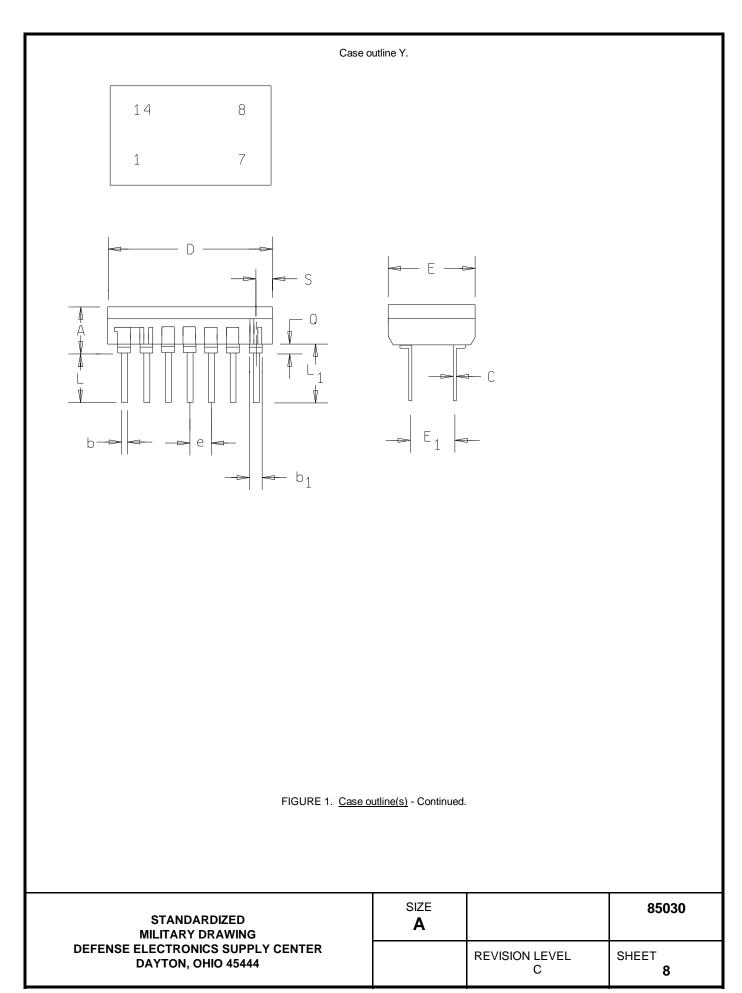
Dimensions					
Symbol	Inches	Inches Millimeters		Millimeters	
	Min	Max	Min	Max	
_A	.215	.250	5.46	6.35	
A <sub>1</sub>	.175	.215	4.44	5.46	
b	.016	.020	0.41	0.51	8
Φ <sub>b</sub>	.016	.020	0.41	0.51	4
D	.860	.885	21.84	22.48	4
E	.490	.520	12.45	13.21	7
E <sub>1</sub>	.295	.305	7.49	7.75	
е	.100 BS	С	2.54 BSC	,	5, 8
L	.130	.255	3.30	6.48	
L <sub>1</sub>	.150	.290	3.81	7.37	
Q	.020	.035	0.51	0.89	3
S	.100	.160	2.54	4.07	
s <sub>1</sub>	.080	.180	2.03	4.57	
α	0°	15°	0°	15°	

## NOTES:

- 1. Index area: A notch, square-package corner, or a pin one index point shall be located adjacent to pin one and within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.
- 2. Dimension Q shall be measured from the seating plane to the base plane.
- 3. This dimension allows for off-center lid, meniscus, and weld squash.
- 4. The basic pin spacing is .100 inch (2.54 mm) between centerlines. Each pin centerline shall be located within ±.010 inch (0.25 mm) of its exact longitudinal position relative to pins 1 and 14.
- 5. Dimension  $S_1$  is not used.
- 6. Lead center when  $a = 0^{\circ}$ . E<sub>1</sub> shall be measured at the centerline of the leads (see MIL-STD-1835).
- 7. All leads: Increase maximum limit by .003 inch (0.08 mm) measured at the widest diameter when lead finish A or B is applied.
- 8. If this configuration is used, no polymer or organic materials shall be applied or molded to the bottom of the package or cover the leads.

FIGURE 1. Case outline(s) - Continued.

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### Case outline Y - Continued.

Dimensions					
Symbol	Inches		Millimeters		Notes
	Min	Max	Min	Max	
A	.140	.200	3.56	5.08	
b	.014	.023	0.36	0.58	
b <sub>1</sub>	.030	.070	0.76	1.78	2
С	.008	.015	0.20	0.38	
D	.770	.810	19.56	20.57	
E	.480	.510	12.19	12.95	
E <sub>1</sub>	.295	.305	7.49	7.75	6
е	0.100 BS	С	2.54 BSC	<b>)</b>	4, 7
L	.150	.200	3.81	5.08	
L <sub>1</sub>	.180		4.57		
Q	.015	.035	0.38	0.89	3
S		.137		3.48	5
S <sub>1</sub>	.060		1.52		5

## NOTES:

- 1. Index area: A notch or a lead one identification mark is located adjacent to lead one.
- 2. The minimum limit for dimension  $b_1$  may be .023 inch (0.58 mm) for all four corner leads only.
- 3. Dimension Q shall be measured from the seating plane to the base plane.
- 4. The basic pin spacing is .100 inch (2.54 mm) between centerlines.
- 5. Applies to all four corners.
- 6. E<sub>1</sub> shall be measured at the centerline of all the leads.

FIGURE 1. Case outline(s) - Continued.

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# Device types 01 and 02.

# Device types 03 and 04.

	2700	
Terminal number	Terminal symbol	
Case outlines	C, X, Y	Z
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27 28	NC NC NC NC NC NC NC TEST POINT VCC +10 V ADJ +10 V ADJ	VO SEN -IN REF GND GND SEN NC

	2702	
Terminal number	Terminal symbol	
Case outlines	C, X, Y	Z
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27	-10 V ADJ -10 V OUT -10 V ADJ VEE NC NC GND NC TEST POINT VCC +10 V ADJ +10 V OUT +10 V ADJ	VO SEN -IN REF GND GND SEN NC NC -VOS -VOS VEE +IN VCC NC -IN VO FORCE -10 V REF OUT VO SENSE +10 V IN VZ ZENER GND NC NC VOS VOS POWER GND VCC +IN
27 28		V <sub>O</sub> FORCE +10 V REF OUT

# FIGURE 2. <u>Terminal connections</u>.

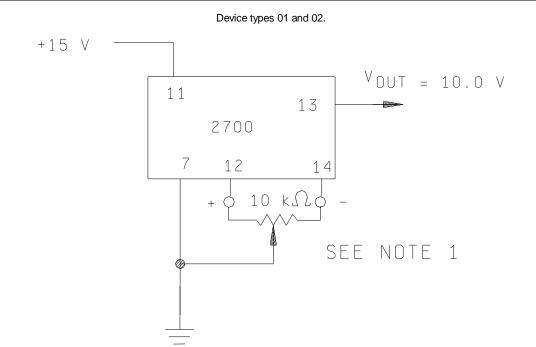
STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE <b>A</b>		85030
		REVISION LEVEL C	SHEET 10

# Device types 05 and 06.

	2701	
Terminal number	Terminal symbol	
Case outlines	C, X, Y	Z
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27 28	NC NC NC NC NC NC NC TEST POINT VEE -10 V ADJ -10 V ADJ	NC REF GND GND SENSE NC NC -VOS -VOS VEE +IN NC PWR GND -IN VO FORCE VO SENSE NC VZ ZENER GND NC

FIGURE 2. <u>Terminal connections</u> - Continued.

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DAYTON, OHIO 45444		C	11



# Device types 03 and 04.

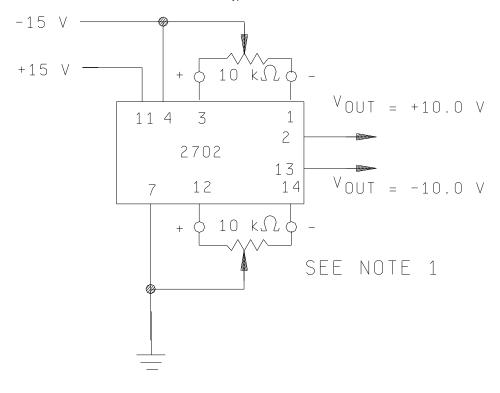
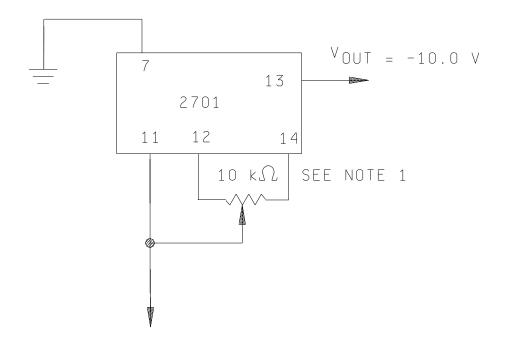


FIGURE 3. Trim circuit(s).

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# NOTES:

- 1. External 10 k $\Omega$  potentiometer provides a  $\pm 20$  mV minimum output offset adjust. Temperature effect is 4  $\mu$ V/ $^{\circ}$ C per mV of offset correction (external adjustment optional).
- 2. Dual-in-line package only.

FIGURE 3. Trim circuit(s) - Continued.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with method 5008, group test table)
Interim electrical parameters	
Final electrical test parameters	1*,2,3,4
Group A test requirements	1,2,3,4,5,6
Group C end-point electrical parameters	1

<sup>\*</sup> PDA applies to subgroup 1.

### 4. QUALITY ASSURANCE PROVISIONS

- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-H-38534.
- 4.2 Screening. Screening shall be in accordance with MIL-H-38534. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DESC-EC or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
    - (2)  $\ \ T_A$  as specified in accordance with table I of method 1015 of MIL-STD-883.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

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- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-H-38534 and as specified herein.
- 4.3.1 Group A inspection. Group A inspection shall be in accordance with MIL-H-38534 and as follows:
  - a. Tests shall be as specified in table II herein.
  - b. Subgroups 7, 8, 9, 10, and 11 shall be omitted.
- 4.3.2 Group B inspection. Group B inspection shall be in accordance with MIL-H-38534.

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- 4.3.3 Group C inspection. Group C inspection shall be in accordance with MIL-H-38534 and as follows:
  - a. End-point electrical parameters shall be as specified in table II herein.
  - b. Steady-state life test, method 1005 of MIL-STD-883.
    - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DESC-EC or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
    - (2) T<sub>A</sub> as specified in accordance with table I of method 1005 of MIL-STD-883.
    - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.3.4 Group D inspection. Group D inspection shall be in accordance with MIL-H-38534.
- 5. PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-H-38534.
- 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.
  - 6.5 Comments. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444, or telephone (513) 296-5373.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in QML-38534. Additional sources will be added to QML-38534 as they become available. The vendors listed in QML-38534 have agreed to this drawing and a certificate of compliance (see 3.7 herein) has been submitted to and accepted by DESC-EC.

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### STANDARDIZED MILITARY DRAWING SOURCE APPROVAL BULLETIN

DATE: 92-12-22

Approved sources of supply for SMD 85030 are listed below for immediate acquisition only and shall be added to QML-38534 during the next revision. QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DESC-EC. This bulletin is superseded by the next dated revision of QML-38534.

	I	1	
Standardized	Vendor	Vendor	
military drawing	CAGE	similar	
PIN	number	PIN <u>1</u> /	
0500004CV	22250	LICO700CD/000D	
8503001CX	33256	HS2700SD/883B	
8503001XX	<u>2</u> /	2700SD/883B	
8503001YX	51640	2700SD/883B	
8503001YX	34707	HC2700SD/883B	
85030013X	34707	HC2700SLCC/883B	
8503002CX	33256	HS2700UD/883B	
8503002XX	<u>2</u> /	2700UD/883B	
8503002YX	51640	2700UD/883B	
8503002YX	34707	HC2700UD/883B	
85030023X	34707	HC2700ULCC/883B	
8503003CX	33256	HS2702SD/883B	
8503003XX	<u>2</u> /	2702SD/883B	
8503003YX	51640	2702SD/883B	
8503003YX	34707	HC2702SD/883B	
85030033X	34707	HC2702SLCC/883B	
8503004CX	33256	HS2702UD/883B	
8503004XX	<u>2</u> /	2702UD/883B	
8503004YX	51640	2702UD/883B	
8503004YX	34707	HC2702UD/883B	
85030043X	34707	HC2702ULCC/883B	
8503005CX	33256	HS2701SD/883B	
8503005YX	51640	2701SD/883B	
8503005YX	34707	HC2701SD/883B	
85030053X	34707	HC2701SLCC/883B	
8503006CX	33256	HS2701UD/883B	
8503006YX	51640	2701UD/883B	
8503006YX	34707	HC2701UD/883B	
85030063X	34707	HC2701ULCC/883B	

- 1/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 2/ Inactive for new design, no longer available from manufacturer.

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### STANDARDIZED MILITARY DRAWING SOURCE APPROVAL BULLETIN - Continued.

DATE: 92-12-22

 Vendor CAGE
 Vendor name

 number
 and address

33256 Sipex Corporation

Hybrid Systems Division 22 Linnell Circle Billerica, CA 01821

34031 Analog Devices, Incorporated

Computer Labs Group 7910 Triad Center Drive Greensboro, NC 27409

Point of contact: Assembled Parts Division

7910 Triad Center Drive Greensboro, NC 27409

34707 Hycomp, Incorporated

165 Cedar Hill Street Marlborough, MA 01752

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in this information bulletin.

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